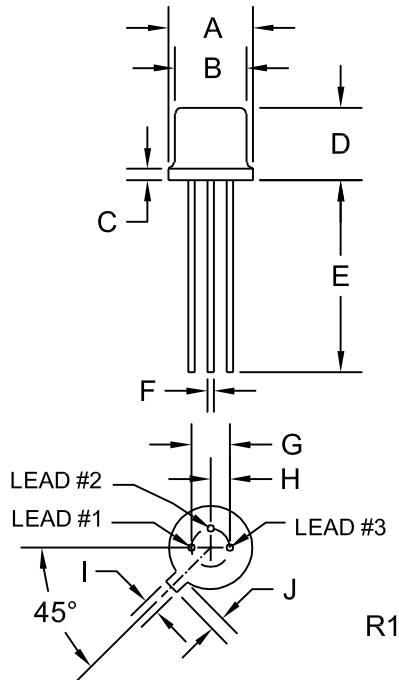


Package Details - TO-18

Mechanical Drawing



SYMBOL	DIMENSIONS			
	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A (DIA)	0.209	0.230	5.31	5.84
B (DIA)	0.178	0.195	4.52	4.95
C	-	0.030	-	0.76
D	0.170	0.210	4.32	5.33
E	0.500	-	12.70	-
F (DIA)	0.016	0.019	0.41	0.48
G (DIA)	0.100		2.54	
H	0.050		1.27	
I	0.036	0.046	0.91	1.17
J	0.028	0.048	0.71	1.22

TO-18 (REV: R1)

LEAD CODE:

SCR

- 1) CATHODE
- 2) GATE
- 3) ANODE

*FET

- | | | |
|-----------|----|-----------|
| 1) SOURCE | | 1) SOURCE |
| 2) GATE | or | 2) DRAIN |
| 3) DRAIN | | 3) GATE |

TRANSISTOR

- 1) EMITTER
- 2) BASE
- 3) COLLECTOR

* Note: See individual device datasheet for pinout information

Packing Code: D

D = White corrugated box with black conductive coating (surface resistivity of $<10^5$ ohms per square).

Standard Packing Quantity: 2K

Material Composition Specification

TO-18 Case



Device average mass 312.4 mg
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.6%	5.0	Si	7440-21-3	1.6%	5.0	16,004
bond wire	alloy	0.125%	0.39	Al	7429-90-5	0.122%	0.38	1,216
				Si	7440-21-3	0.003%	0.01	32
header	Kovar (Fe/Ni/Co alloy)	58.8%	183.71	Fe	7439-89-6	22.161%	69.236	221,615
				Ni	7440-02-0	14.511%	45.334	145,108
				glass	Proprietary	13.444%	42	134,436
				Co	7440-48-4	7.808%	24.392	78,075
				Mn	7439-96-5	0.217%	0.677	2,167
				P	7723-14-0	0.18%	0.561	1,796
				Si	7440-21-3	0.13%	0.406	1,300
				Ag	7440-22-4	0.23%	0.72	2,305
				C	1333-86-4	0.21%	0.067	214
				Cu	7440-50-8	0.09%	0.28	896
S	7704-34-9	0.013%	0.041	131				
can	alloy	36.81%	114.99	Fe	7439-89-6	36.698%	114.65	366,979
				C	1333-86-4	0.017%	0.052	166
				Mn	7439-96-5	0.074%	0.23	736
				Al	7429-90-5	0.019%	0.06	192
can plating	nickel	1.06%	3.32	Ni	7440-02-0	1.06%	3.32	10,627
plating*	tin/lead process	1.6%	5.0	Sn	7440-31-5	1.344%	4.2	13,444
				Pb	7439-92-1	0.256%	0.8	2,561
	100% tin process	1.6%	5.0	Sn	7440-31-5	1.6%	5.0	16,004

*For Lead Free plating, add suffix "LEAD FREE" to part number.
 For Tin/Lead plating, add suffix "TIN/LEAD" to part number.
 No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R1 (3-June 2011)